

Latest Panasonic Packaging Technology and Solutions

Kiyoshi Arita, Panasonic Factory Solutions Co., Ltd.

Panasonic Factory Solutions Co., Ltd. (PFSC) focuses the packaging business from wafer fabrication to Back-end assembly process. Recent electrical products use attractive packages and modules. LED backlight, mobile PC, and smart phone are flagship products. PFSC provides packaging technology and solutions for these production processes.

- Thin LCD TV : LED packaging, backlight module assembly, and LCD panel assembly system
- Mobile PC and smart phone: RF module packaging and High speed SMD assembly system
- Next generation packaging: COW packaging and Plasma dicing

This presentation focuses on advanced process solutions how to achieve the low cost and high quality production. The dry-etcher is used for high power LED element. The flip chip GGI technology is used to improve radiation performance of high power LED. High accuracy multi bonding system can be applied to stacking die application for RF module. PFSC will innovate the next generation packaging with newly developed process and solutions as Plasma dicing and stress relief.